



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-10-09
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
LD3985M33R	MFVV*UT96AA6	A	Z8GA	2015-10-09
Amount		UoM	Unit type	ST ECOPACK Grade
16.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	2.82X1.52X1.25	5	gull wing	
Comment	Package: SOT 23 5L			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MFWV*UT96AA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.881	mg	supplier	die	Silicon (Si)	7440-21-3		0.833	mg	945516	52063
				supplier	metallization	Aluminium (Al)	7429-90-5		0.007	mg	7946	438
				supplier	metallization	Tungsten (W)	7440-33-7		0.012	mg	13621	750
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2270	125
				supplier	Passivation	Silicon Oxide	7631-86-9		0.017	mg	19296	1063
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.001	mg	1135	63
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.009	mg	10216	563
Leadframe	Copper and its alloy	6.377	mg	Supplier	Alloy	Copper(CU)	7440-50-8		6.061	mg	950447	378813
				Supplier	Alloy	Iron(Fe)	7439-89-6		0.147	mg	23052	9188
				Supplier	Alloy	Phosphorus(P)	7723-14-0		0.005	mg	784	313
				Supplier	Alloy	Zinc(Zn)	7440-66-6		0.008	mg	1255	500
				Supplier	Alloy	Silver(Ag)	7440-22-4		0.156	mg	24463	9750
Die Attach	Other Organic Material	0.195	mg	Supplier	Glue	Silver(Ag)	7440-22-4		0.156	mg	800000	9750
				Supplier	Glue	Acrylate resins	7534-94-3		0.027	mg	138462	1688
				Supplier	Glue	Heterocyclic organic compound	3006-93-7		0.006	mg	30769	375
				Supplier	Glue	Treated silica	Proprietary		0.006	mg	30769	375
Bonding wire	Other Inorganic Material	0.061	mg	Supplier	Bonding wire	Gold(Au)	7440-57-5		0.061	mg	1000000	3813
Encapsulation	Other Organic Material	8.034	mg	Supplier	Molding compound	Biphenyl epoxy resin	85954-11-6		0.643	mg	80035	40188
				Supplier	Molding compound	Phenol Resin	26834-02-6		0.321	mg	39955	20063
				Supplier	Molding compound	Silica, vitreous	60676-86-0		6.982	mg	869057	436375
				Supplier	Molding compound	Carbon black	1333-86-4		0.040	mg	4979	2500
				supplier	Molding compound	Bismuth (Bi)	7440-69-9		0.048	mg	5975	3000
Finishing	Other Inorganic Material	0.452	mg	Supplier	Connection Coating	Tin(Sn)	7440-31-5		0.452	mg	1000000	28250